

IN THE SPECIFICATION:

Please amend the paragraph starting at page 23, line 12 and ending at page 24, line 14, as follows:

First, a substrate 100 on which row directional wiring electrodes 108, column directional wiring electrodes 109, an interelectrode insulating layer (not shown), and surface conduction type electron-emitting devices 107 (each including device electrodes and conductive thin film) are formed in advance is fixed onto a rear plate (glass substrate) 101. Next, the spacers formed as described above (rear plate side spacers) are fixed onto the row directional wiring electrodes 108 of the substrate 100 at regular intervals in parallel to the row directional wiring electrodes 108, and then the grid is bonded to the rear plate side spacers. After that, the spacers (face plate side spacers) are bonded to the face plate 102 in which a phosphor 104 and a metal back 105 is provided on the inner surface thereof of glass plate 103. Then, the face plate 102 is located above the substrate 100 by 1.6 mm through a side wall 106, and respective bonding regions among the rear plate 101, the face plate 102, the side wall 106, and the spacers are fixed to one another. A bonding region between the substrate 100 and the rear plate 101, and a bonding region between the rear plate 101 and the side wall 106, ~~and a bonding region between the face plate 102 and the side wall 106~~ are sealed by applying frit glass (not shown) to these bonding regions and baking in an atmosphere at 400°C to 500°C for 10 or more minutes. Thus the envelope 110 is formed. Further, an inside of the ~~display panel~~ envelope 110 is evacuated. Thus, the display panel is completed.